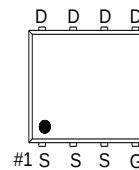
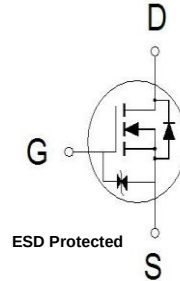


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	18m Ω	24A



G. GATE
D. DRAIN
S. SOURCE

100% UIS Tested
100% Rg Tested

Features

- Pb-Free, Halogen Free and RoHS compliant.
- Low $R_{DS(on)}$ to Minimize Conduction Losses.
- Ohmic Region Good $R_{DS(on)}$ Ratio.
- Optimized Gate Charge to Minimize Switching Losses.
- Products Integrated ESD diode with ESD Protected up to 2KV.

Applications

- Protection Circuits Applications.
- Computer for DC to DC Converters Applications.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ⁴	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	24	A
	$T_C = 100\text{ }^{\circ}\text{C}$		15	
Pulsed Drain Current ¹		I_{DM}	36	
Continuous Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	7.8	
	$T_A = 70\text{ }^{\circ}\text{C}$		6.2	
Avalanche Current ⁵		I_{AS}	21.4	mJ
Avalanche Energy ⁵	$L = 0.02\text{mH}$	E_{AS}	4.6	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	19	W
	$T_C = 100\text{ }^{\circ}\text{C}$		7.7	
Power Dissipation ³	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	2	W
	$T_A = 70\text{ }^{\circ}\text{C}$		1.3	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$t \leq 10s$	$R_{\theta JA}$		62	°C / W
Junction-to-Ambient ²	Steady-State	$R_{\theta JA}$		96	
Junction-to-Case	Steady-State	$R_{\theta JC}$		6.5	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

³The Power dissipation is based on $R_{\theta JA}$ $t \leq 10s$ value.

⁴The maximum current rating is package limited.

⁵ $V_{DD} = 50V$, $V_{GS} = 10V$, starting $T_J = 25^\circ\text{C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL		TEST CONDITIONS	LIMITS			UNIT
				MIN	TYP	MAX	
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}		V _{GS} = 0V, I _D = 250μA	30			V
Gate Threshold Voltage	V _{GS(th)}		V _{DS} = V _{GS} , I _D = 250μA	1.3	1.75	2.2	
Gate-Body Leakage	I _{GSS}		V _{DS} = 0V, V _{GS} = ±16V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}		V _{DS} = 24V, V _{GS} = 0V			1	μA
			V _{DS} = 20V, V _{GS} = 0V, T _J = 55 °C			10	
Drain-Source On-State Resistance ¹	R _{DS(ON)}		V _{GS} = 4.5V, I _D = 6A		18	27	mΩ
			V _{GS} = 10V, I _D = 7A		13	18	
Forward Transconductance ¹	g _{fs}		V _{DS} = 5V, I _D = 7A		37		S
DYNAMIC							
Input Capacitance	C _{iss}		V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		376		pF
Output Capacitance	C _{oss}				76		
Reverse Transfer Capacitance	C _{rss}				48		
Gate Resistance	R _g		V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		3.1		Ω
Total Gate Charge ²	Q _g	V _{GS} = 10V	V _{DS} = 15V , V _{GS} = 10V, I _D = 7A		7.6		nC
		V _{GS} = 4.5V			4.2		
Gate-Source Charge ²	Q _{gs}				1		
Gate-Drain Charge ²	Q _{gd}				1.9		
Turn-On Delay Time ²	t _{d(on)}		V _{DS} = 15V , I _D ≅ 7A, V _{GS} = 10V, R _{GEN} =6 Ω		5.5		nS
Rise Time ²	t _r				35		
Turn-Off Delay Time ²	t _{d(off)}				15		
Fall Time ²	t _f				46		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)

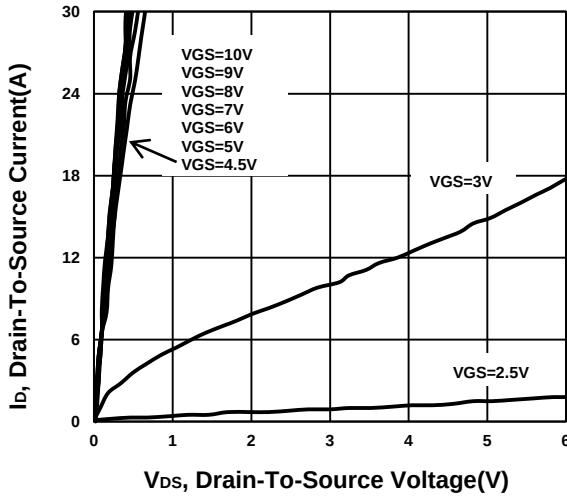
Continuous Current ³	I _S			17	A
Forward Voltage ¹	V _{SD}	I _F = 7A, V _{GS} = 0V		1.1	V
Reverse Recovery Time	t _{rr}	I _F = 7A, dI _F /dt = 100A / μS	4.7		nS
Reverse Recovery Charge	Q _{rr}		0.9		nC

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

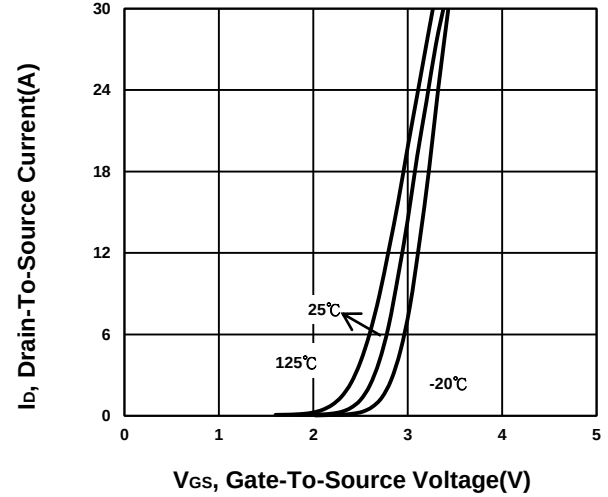
²Independent of operating temperature.

³The maximum current rating is package limited.

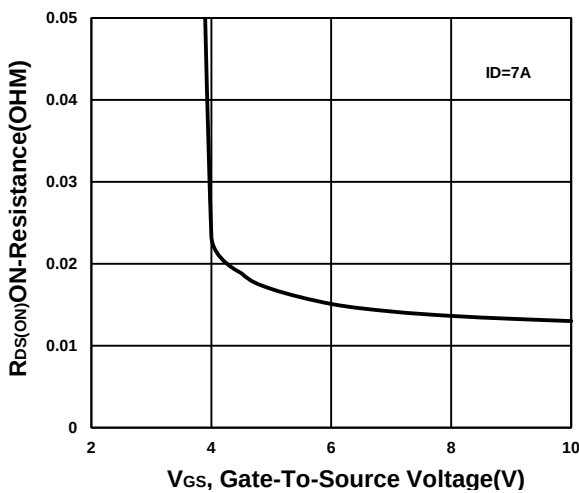
Output Characteristics



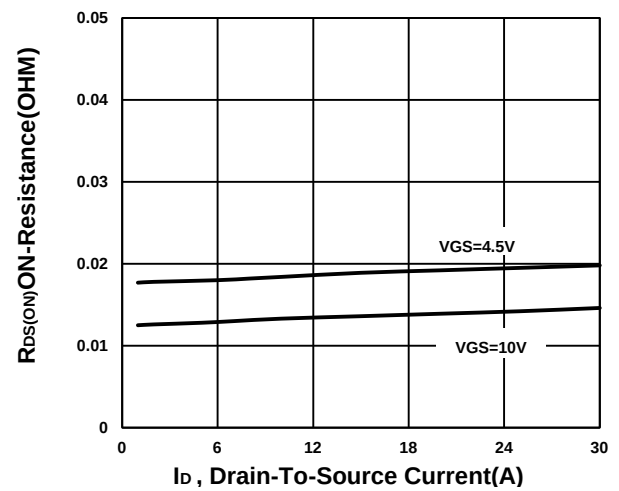
Transfer Characteristics



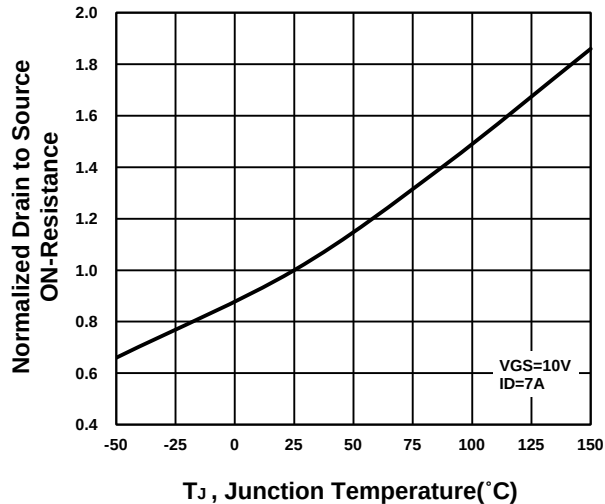
On-Resistance VS Gate-To-Source Voltage



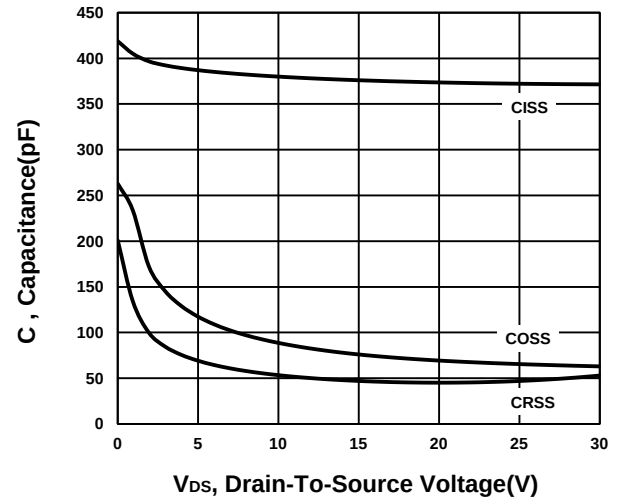
On-Resistance VS Drain Current

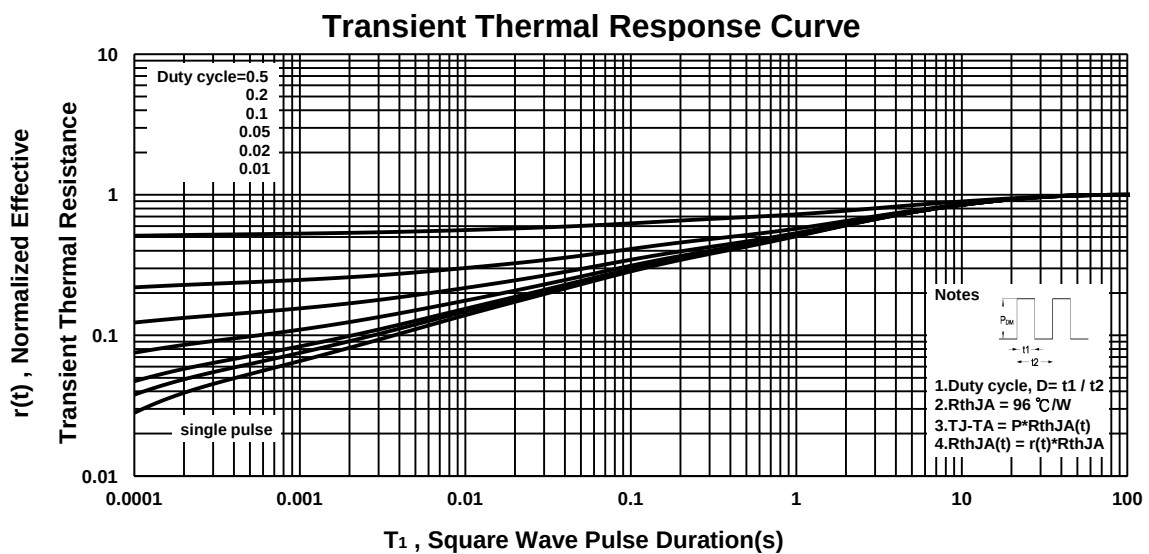
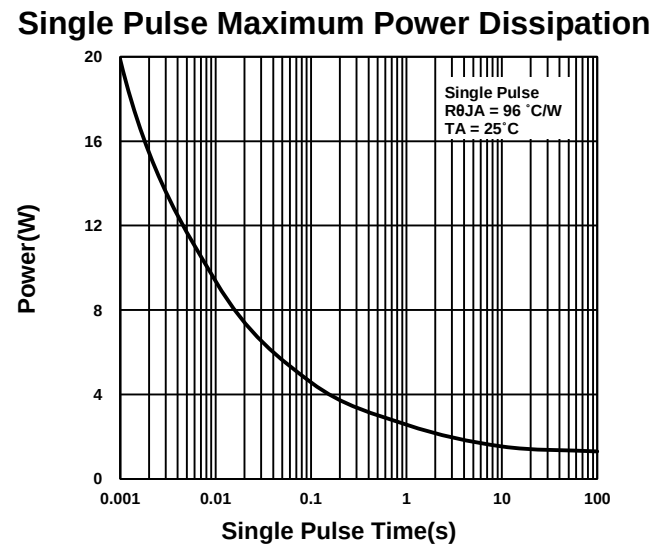
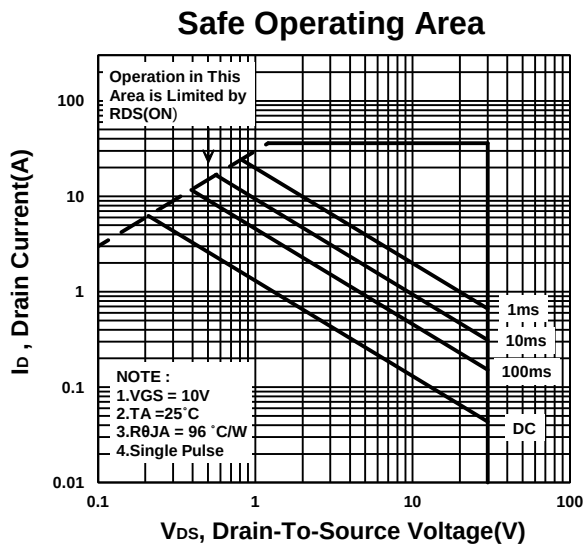
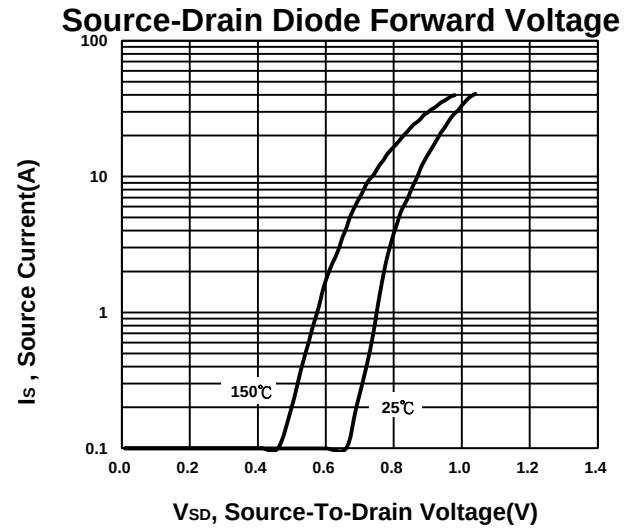
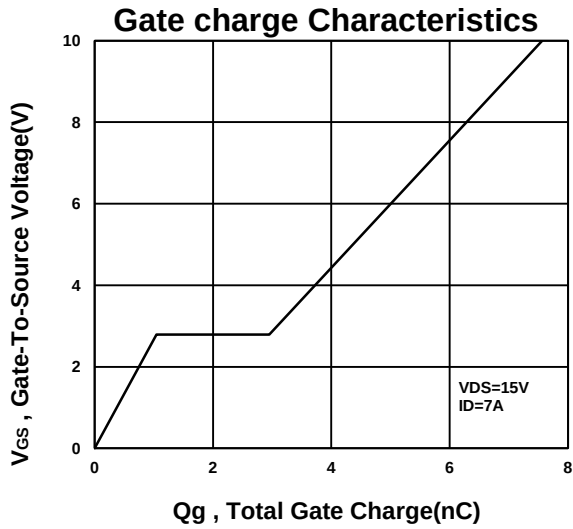


On-Resistance VS Temperature

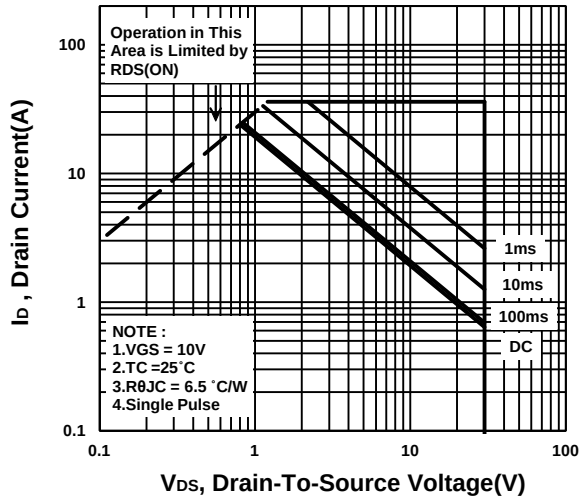


Capacitance Characteristic

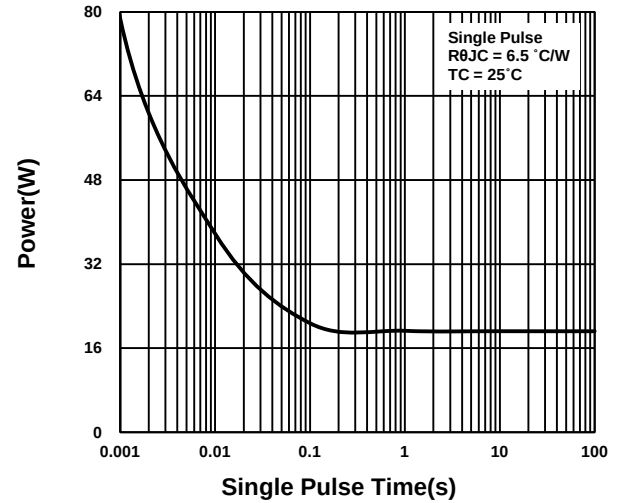




Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

